

### **REMARKS**

Claims 18 and 21-25 remain in the application for consideration of the Examiner.

Reconsideration and withdrawal of the outstanding rejections are respectfully requested in light of the above amendments and following remarks.

Claim 24 was rejected under 35 U.S.C. § 112, first paragraph, as failing to comply with the written requirement.

The Examiner alleges that this claim contains subject matter not described in the specification.

Claim 24 includes the step of plating at least one additional layer on the said second layer of metal.

However, the Examiner's attention is directed to page 9, line 12 et seq of the instant application.

The Examiner's concern with respect to the second tool or the same embossing tool is not understood since this does not relate to the subject matter of Claim 24.

It is respectfully submitted that Claim 24 is in full compliance with 35 U.S.C. § 112, first paragraph.

Claim 24 was rejected under 35 U.S.C. § 112, second paragraph, as being indefinite.

The Examiner alleges that it is unclear whether the same embossing tool or another embossing tool is used to perform the step (a) on the second surface of the film.

Again, Claim 24 recites the step of plating at least one additional layer on the second layer of metal.

Claim 24 does not relate to the same embossing tool or another embossing tool and consequently the rejection under 35 U.S.C. § 112, second paragraph, is not understood.

It is respectfully submitted that Claims 18 and 21-25 are in full compliance with 35 U.S.C. § 112 and particularly points out and distinctly claims the subject matter which Applicants believe is their invention.

Claims 21-23 and 24 were rejected under 35 U.S.C. § 102(e) as being anticipated by Sumi; and Claim 24 was rejected under 35 U.S.C. § 103 as being unpatentable over Sumi in view of Chong.

These rejections are respectfully traversed.

It is respectfully submitted that Sumi does not disclose or suggest the presently claimed invention including the steps of positioning adjacent to the film a single embossing tool and applying heat and pressure on the tool to simultaneously emboss the film.

Sumi does not disclose a single embossing tool which could perform simultaneously embossing applying heat and pressure on the tool.

Whether or not Chong discloses plating additionally layer on the second layer and whether or not one of ordinary skill in the art would consider modifying Sumi is of no moment since the resulting construction would still in no way disclose or suggest the presently claimed invention.

Applicants appreciate the indication that Claim 18 is allowed.

In light of the above, it is respectfully submitted that the present application is in condition for allowance, and notice to that effect is respectfully requested.

While it is believed that the instant amendment places the application in condition for allowance, should the Examiner have any further comments or suggestions, it is respectfully requested that the Examiner contact the undersigned in order to expeditiously resolve any outstanding issues.

To the extent necessary, Applicant petitions for an Extension of Time under 37 CFR 1.136. Please charge any fees in connection with the filing of this paper, including extension of time fees, to the deposit account of Texas Instruments Incorporated, Account No. 20-0668.

Respectfully submitted,



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